



PolyStrata[®] Package

Nuvotronics presents a new state of the art low loss MMIC package. The PolyStrata[®] package complements integrated MMIC performance and can be surface mounted to a PCB using standard SMT processes. This increases the ease of manufacturing while maintaining superior performance in a smaller size compared to other packaging substrates.

Features and Benefits

- Ultra-Low Loss
- Ideal thermal performance due to solid copper construction
- Chip interface compatible with automated Au wire bonding
- PCB interface compatible with standard SMT processes

Applications

- Military
- Space
- Communications
- Instrumentation

Part Number	Single Sided Transition Performance			Max Die Size			Package Size			DC Pins	Lead Time (if not in stock)
	Max Frequency (GHz)	Insertion Loss (dB)	Return Loss (dB)	X (mm)	Y (mm)	Z (mm)	X (mm)	Y (mm)	Z (mm)		
PSP1025530_002	21 GHz	0.2 dB	20dB	2.1	1.3	0.08	6.34	3.896	0.7	6	13 weeks
PSP1025530_003	40 GHz	0.3 dB	20dB	3.55	5.965	0.18	6.79	10.39	0.85	4	15 weeks
PSP1028104*	95 GHz	0.5 dB	20dB	5	5	0.1	10	10	0.7	12	13 weeks
PSP1028105*	95 GHz	0.5 dB	20dB	4	3.75	0.1	8	8	0.7	12	13 weeks
PSP1028106*	95 GHz	0.5 dB	20dB	3.25	3.25	0.1	7	7	0.7	12	13 weeks
PSP1028107*	95 GHz	0.5 dB	20dB	2.55	2.55	0.1	6	6	0.7	10	13 weeks
PSP1028108*	95 GHz	0.5 dB	20dB	1.6	1.6	0.1	5	5	0.7	8	13 weeks
PSP1028109*	50 GHz	0.3 dB	20dB	5	5	0.1	7	7	0.4	12	9 weeks
PSP1028110*	50 GHz	0.3 dB	20dB	4	4	0.1	6	6	0.4	10	9 weeks
PSP1028111*	50 GHz	0.3 dB	20dB	3	3	0.1	5	5	0.4	8	9 weeks
PSP1028112*	50 GHz	0.3 dB	20dB	2	2	0.1	4	4	0.4	6	9 weeks
PSP1028113*	50 GHz	0.3 dB	20dB	1	1	0.1	3	3	0.4	4	9 weeks

*In development